25
B
7.394
7.194
C
A1 INDEX
3 4
CAPACITOR
ZONES
4X
8X 6.5 MAX
8.1
7.9
25
UNDERFILL ZONE
4X 0.2
4X 8 MIN
4X 11.3 MAX

TOP VIEW

0.15 A
A
SEATING
PLANE
5
// 0.25 A
// 0.35 A

18X 1.27
W V U T R P N M L K J H G F E D C B A
18X 1.27
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19
360X ø0.9
0.6
6
ø0.3 M A B C
ø0.15 M A

4X 0.6 MAX
0.6
0.4
0.9
0.82
0.9
0.7
2.4 MAX

BOTTOM VIEW

SIDE VIEW

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TITLE: 360 I/O FC CBGA, 25 X 25 PKG, 1.27MM PITCH, WITH CAP ZONES	DOCUMENT NO: 98ARE10604D REV: B	
	STANDARD: NON-JEDEC	
	SOT1603-3 17 DEC 2015	

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

2. ALL DIMENSIONS IN MILLIMETERS.

3. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

4. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

5. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. MAXIMUM SOLDER BALL DIAMETER IS MEASURED PARALLEL TO DATUM A.

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